



Material Content Data Sheet



Sales Product Name		SPB21N50C3		Issued		2. August 2018		
MA#		MA000737484						
Package		PG-TO263-3-2		Weight*		1564.41 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	13.322	0.85	0.85	8516	8516
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		58	
	non noble metal	iron	7439-89-6	0.304	0.02		195	
	non noble metal	copper	7440-50-8	304.026	19.43	19.46	194339	194592
	non noble metal	aluminium	7429-90-5	2.786	0.18	0.18	1781	1781
wire	non noble metal	aluminium	7429-90-5	2.786	0.18	0.18	1781	1781
encapsulation	organic material	carbon black	1333-86-4	10.162	0.65		6496	
	plastics	epoxy resin	-	111.781	7.15		71452	
	inorganic material	silicondioxide	60676-86-0	555.516	35.50	43.30	355095	433043
leadfinish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6173	6173
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	146	147
solder	non noble metal	tin	7440-31-5	0.163	0.01		104	
	noble metal	silver	7440-22-4	0.204	0.01		130	
	non noble metal	lead	7439-92-1	7.791	0.50	0.52	4980	5214
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		105	
	non noble metal	iron	7439-89-6	0.548	0.04		351	
	non noble metal	copper	7440-50-8	547.666	35.01	35.06	350078	350534
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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